

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended) A heat regulating device for regulating a heat flow into and out of an integrated circuit semiconductor body comprising:  
a plurality of thermo-electrical ~~structure~~ structures that create a uniform temperature gradient across an integrated circuit semiconductor body via heat inducement to and/or dissipation of ~~induces heat to and /or dissipates~~ generated heat away from a portion of ~~an~~ the integrated circuit semiconductor body;  
at least one layer of a conductive material in contact with the plurality of thermo-electrical ~~structure~~ structures for conducting heat flow.
2. (Currently Amended) A heat regulating device according to claim 1, each of the thermo-electrical ~~structure~~ structures is a trough within the body of the layer of the conductive material.
3. (Currently Amended) A heat regulating device according to claim 1, ~~further comprising a~~ the plurality of the thermo-electrical structures ~~connected to~~ form a spreading assembly.
4. (Original) A heat regulating device according to claim 3, the spreading assembly is operatively connected to a heat sink.
5. (Currently Amended) A heat regulating device according to claim 1, each of the thermo-electrical ~~structure~~ structures is a conductive pathway for heat transfer.
6. (Currently Amended) A heat regulating device according to claim 1, each of the thermo-electrical ~~structure~~ structures has a structure of line patterns selected from a group comprising: maze-shaped structure, helix structure, and a spring structure.

7. (Currently Amended) A heat regulating device for regulating a heat flow of an integrated circuit comprising:

means for inducing heat into a portion of a semiconductor body of the integrated circuit utilizing a plurality of thermo-electric ~~[[structure]]~~ structures; and/or

means for dissipating heat away from a portion of a semiconductor body of the integrated circuit utilizing a plurality of thermo-electric ~~[[structure]]~~ structures;

the heat inducing means and/or heat dissipating means create a uniform temperature gradient across the semiconductor body; and

heat conducting means in contact with the means for inducing heat into or dissipating heat away from the portion of the semiconductor body.

8-22. (Cancelled)

23. (Currently Amended) A heat regulating device according to claim 3, with components embedded into the spreading assembly to manage the heat flow away from and/or into the integrated circuit semiconductor body.

24. (Currently Amended) A heat regulating device according to claim 6, each of the thermo-electrical ~~structure having~~ structures has a denser distribution of line patterns towards the center of the structure and a less dense distribution of lines towards the outer limits of the structure.

25. (Currently Amended) A heat regulating device according to claim 1, each of the thermo-electrical ~~structure~~ structures being embedded with measuring devices to measure various physical properties of the integrated circuit semiconductor body.

26. (Currently Amended) A heat regulating device according to claim 1, each of the thermo-electrical ~~structure~~ structures being an external element attached to the surface of the heat regulating device.

27. (Previously Presented) A heat regulating device according to claim 1, fabricated from a combination of various layers of silicon carbide and diamond.
28. (Withdrawn) A method of reducing the accumulation and concentration of stress in ICs comprising:
- providing an integrated circuit with a semiconductor chip having hot spots generated therein with a heat regulating device including:
    - a thermo-electrical structure for at least one of inducing heat into and dissipating generated heat away from a region of a semiconductor body; and
    - at least one layer of a conductive material in contact with the thermo-electrical structure for conducting heat flow.
29. (Withdrawn) The method of claim 28, further comprising creating a uniform temperature gradient throughout the semiconductor body.
30. (Withdrawn) The method of claim 29, the uniform temperature gradient being created by inducing heat into various regions of the semiconductor body.
31. (Withdrawn) The method of claim 29, the uniform temperature gradient being created by dissipating heat from the hot spots into the layer of conductive material of the heat regulating device.
32. (Currently Amended) A heat regulating device according to claim 1, each of the thermo-electrical ~~structure~~ structures is a composite composed of a layer having at least one part tailored to a heat-generating characteristic of a portion of the integrated circuit semiconductor body.
33. (Previously Presented) A heat regulating device according to claim 1, at least one thermo-electric structure is integrated with the semiconductor body such that the thermo-electrical structure is positioned in a region of the semiconductor body where a hot spot is anticipated.

34. (Currently Amended) A system that facilitates reducing the accumulation and concentration of stress in an integrated circuit, comprising:

~~means for inducing heat into a region of a semiconductor body of the an integrated circuit;~~

~~means for dissipating generated heat away from a region of a semiconductor body of the integrated circuit; and~~

means for creating a uniform temperature gradient throughout the integrated circuit based at least in part upon one of ~~the~~ a heat dissipation and ~~the~~ a heat induction.